

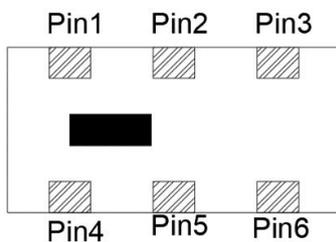
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

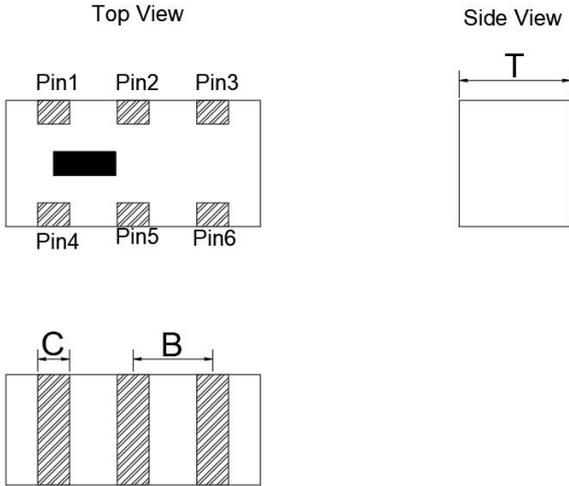
NO.	Parameter	SPEC
1	Frequency range	699~960 MHz
2	Insertion Loss	0.85 dB max. at +25°C
		0.95 dB max. at -40°C ~ +85°C
3	Attenuation	30 dB min. @ 1427~1920 MHz
		30 dB min. @ 2097~2880 MHz
4	VSWR (In BW)	2.0 max.
5	Port Impedance	50Ω
6	Power	1W max.
7	Operation Temperature Range	-40°C ~ +85°C

Construction

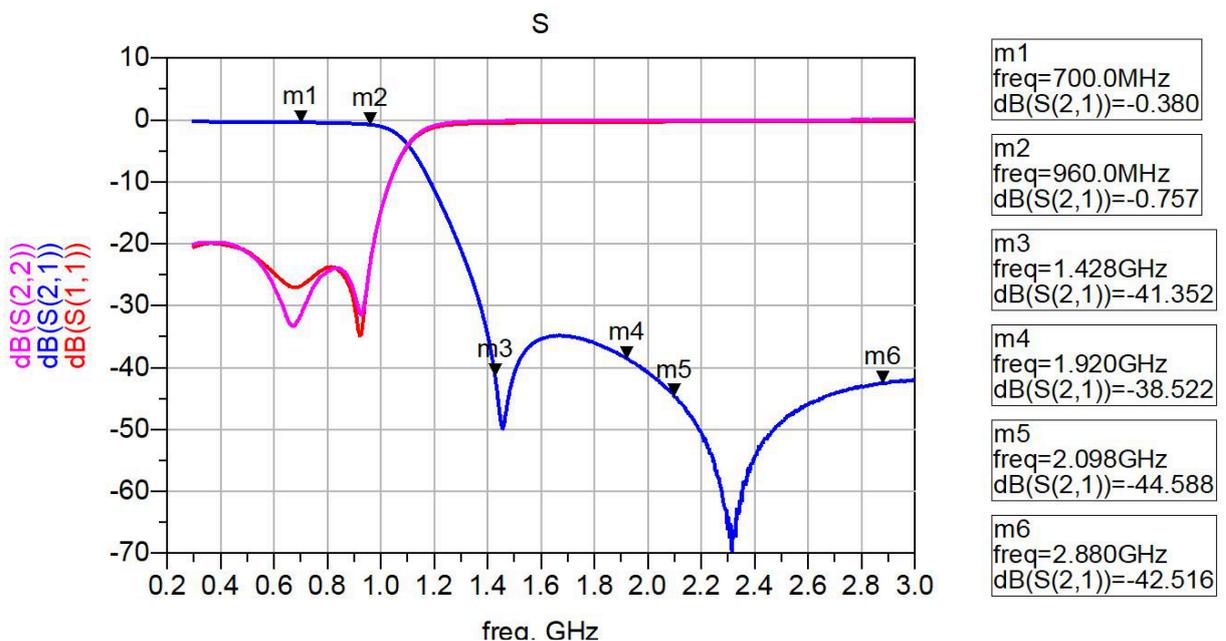


PIN	Connection
1	Input port
2	GND
3	Output port
4	GND
5	NC
6	GND

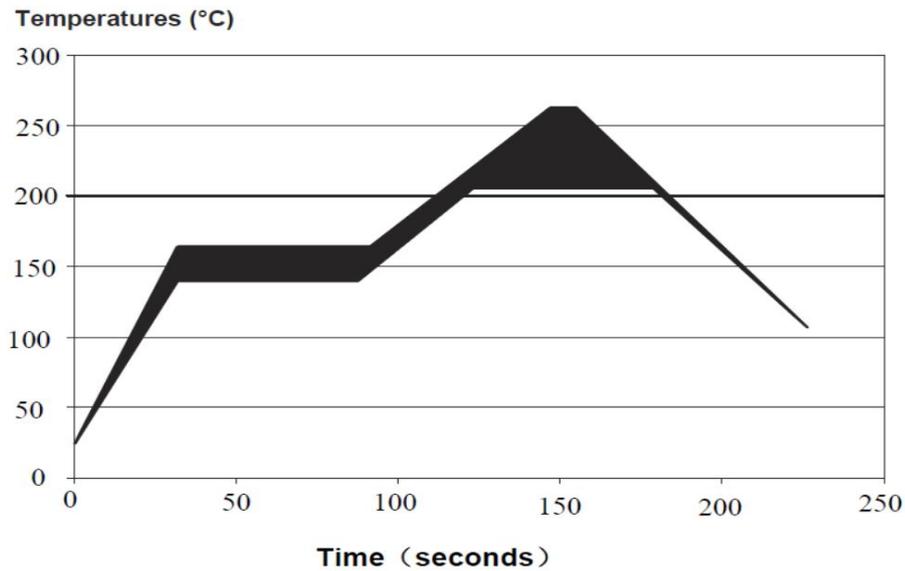
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.65 ± 0.10
	B	0.225 ± 0.10
	C	0.40 ± 0.10
	D	0.30 ± 0.10
	E	0.22 ± 0.10
F	0.21 ± 0.10	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.